

3A, 50V - 1000V Surface Mount Rectifier

FEATURES

- Glass passivated chip junction
- Ideal for automated placement
- Low forward voltage drop
- High current capability
- High surge current capability
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- Switching mode power supply (SMPS)
- Adapters
- Lighting application
- Converter

MECHANICAL DATA

- Case: DO-214AB (SMC)
- Molding compound meets UL 94V-0 flammability rating
- Part no. with suffix "H" means AEC-Q101 qualified
- Packing code with suffix "G" means green compound (halogen-free)
- Moisture sensitivity level: level 1, per J-STD-020
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: As marked
- Weight: 0.21 g (approximately)

KEY PARAMETERS					
PARAMETER	VALUE	UNIT			
$I_{F(AV)}$	3	Α			
V_{RRM}	50 - 1000	V			
I _{FSM}	100	Α			
$T_{J MAX}$	150	°C			
Package	DO-214AB (SMC)				
Configuration	Single die				





DO-214AB (SMC)

PARAMETER	SYMBOL	S3A	S3B	S3D	S3G	S3J	S3K	S3M	UNIT
Marking code on the device		S3A	S3B	S3D	S3G	S3J	S3K	S3M	
Repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Reverse voltage, total rms value	V _{R(RMS)}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Forward current	I _{F(AV)}	3			Α				
Surge peak forward current, 8.3 ms single half sine-wave uperimposed on rated load per diode	I _{FSM}	100				А			
Junction temperature	TJ	- 55 to +150				°C			
Storage temperature	T _{STG}	- 55 to +150				°C			

1



THERMAL PERFORMANCE						
PARAMETER	SYMBOL	TYP	UNIT			
Junction-to-lead thermal resistance per diode	$R_{\Theta JL}$	13	°C/W			
Junction-to-ambient thermal resistance per diode	$R_{\Theta JA}$	47	°C/W			

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	TYP.	MAX.	UNIT	
Forward voltage per diode (1)	I _F = 3A, T _J = 25°C	V _F	-	1.15	V	
Reverse current @ rated V _R per diode ⁽²⁾	T _J = 25°C		-	10	μA	
Reverse current @ rated v _R per diode	T _J = 125°C	l _R	-	250	μA	
Junction capacitance	1 MHz, V _R =4.0V	CJ	60	-	pF	
Reverse recovery time	I _F =0.5A , I _R =1.0A I _{RR} =0.25A	t _{rr}	1500	-	ns	
•	I _{RR} =0.25A	-11				

Notes:

- 1. Pulse test with PW=0.3 ms
- 2. Pulse test with PW=30 ms

ORDERING INFORMATION						
PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING	
		R7		SMC	850 / 7" Plastic reel	
		R6		SMC	3,000 / 13" Paper reel	
S3x (Note 1,2)	Н	M6	G	SMC	3,000 / 13" Plastic reel	
(14018 1,2)		V7		Matrix SMC	850 / 7" Plastic reel	
		V6		Matrix SMC	3,000 / 13" Plastic reel	

Note:

- 1. "x" defines voltage from 50V (S3A) to 1000V (S3M)
- 2. Only V6 and V7 are all green compound (halogen free)

EXAMPLE					
EXAMPLE P/N	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
S3AHR7G	S3A	Н	R7	G	AEC-Q101 qualified Green compound



CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

RESISTIVE OR INDUCTIVE LOAD

50

25

0.5

0

Fig.1 Forward Current Derating Curve 3.5 AVERAGE FORWARD CURRENT (A) 3 2.5 2 1.5 1

Fig.2 Typical Junction Capacitance

Fig.3 Typical Reverse Characteristics

75

LEAD TEMPERATURE (°C)

100

125

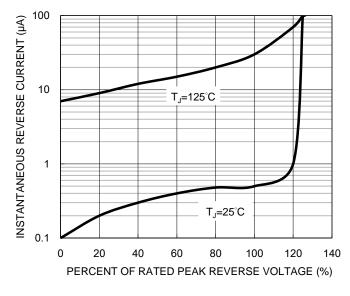


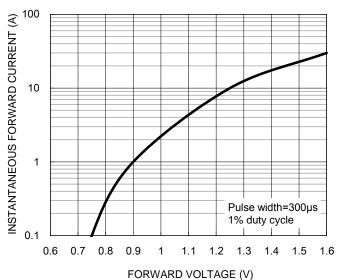
Fig.4 Typical Forward Characteristics

1

REVERSE VOLTAGE (V)

10

100



100

CAPACITANCE (pF)

150

f=1.0MHz Vsig=50mVp-p

0.1

0.01



CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

Fig.5 Maximum Non-repetitive Forward Surge Current

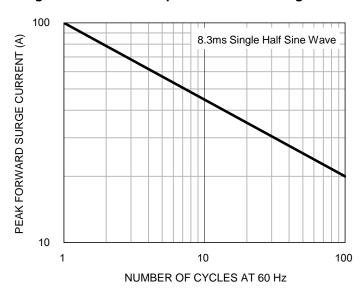
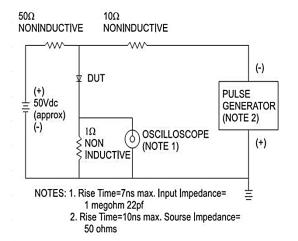
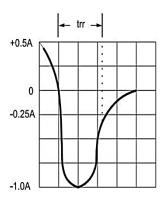


Fig.6 Reverse Recovery Time Characteristic And Test Circuit Diagram

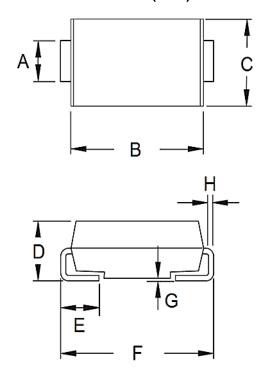






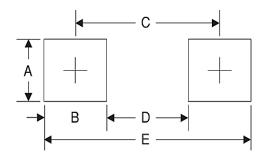
PACKAGE OUTLINE DIMENSIONS

DO-214AB (SMC)



DIM	Unit	(mm)	Unit (inch)		
DIM.	Min	Max	Min	Max	
Α	2.90	3.20	0.114	0.126	
В	6.60	7.11	0.260	0.280	
С	5.59	6.22	0.220	0.245	
D	2.00	2.62	0.079	0.103	
Е	1.00	1.60	0.039	0.063	
F	7.75	8.13	0.305	0.320	
G	0.10	0.20	0.004	0.008	
Н	0.15	0.31	0.006	0.012	

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
А	3.30	0.130
В	2.50	0.098
С	6.80	0.268
D	4.40	0.173
Е	9.40	0.370

MARKING DIAGRAM

Matrix SMC SMC





P/N =Marking Code G =Green Compound

YW =Date Code F =Factory Code

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Version:M1903



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S3K V7G
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